

# **OCTAL BUS SWITCH**

# **FEATURES:**

- Bus switches provide zero delay paths
- Low switch on-resistance
- TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Hot insertion capability
- Very low power dissipation
- Available in QSOP, SOIC, SSOP, and TSSOP Packages

# **DESCRIPTION:**

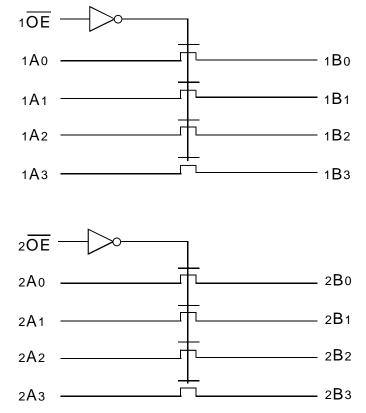
The FST3244 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts or the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no VCC applied, the device has hot insertion capability.

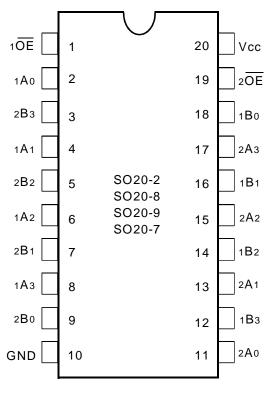
The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST3244 is an octal TTL-compatible bus switch. The  $\overline{\text{OE}}$  pins provide output enable control for all 8 bits. This device is pin-compatible with and functionally similar to the FCT244T.

# **FUNCTIONAL BLOCK DIAGRAM**

# **PIN CONFIGURATION**





QSOP/ SOIC/ SSOP/ TSSOP TOP VIEW

## INDUSTRIAL TEMPERATURE RANGE

**APRIL 2001** 

# **ABSOLUTE MAXIMUM RATINGS**(1)

Symbol	Rating	Max.	Unit
VTERM(2)	Terminal Voltage with Respect to GND	-0.5 to +7	٧
Tstg	Storage Temperature	-65 to +150	°C
Іоит	Maximum Continuous Channel Current	128	mA

#### FST LINK

### NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Vcc, Control, and Switch terminals.

# **CAPACITANCE** (1)

Symbol	Parameter	Conditions(2)	Тур.	Unit
CIN	Control Input Capacitance		8	pF
CI/O	Switch Input/Output	Switch Off	13	pF
	Capacitance			

### NOTES:

- 1. Capacitance is characterized but not tested.
- 2. TA = 25°C, f = 1MHz, VIN = 0V, VOUT = 0V

# PIN DESCRIPTION

Pin Names	Description
xŌĒ	Output Enable Inputs (Active LOW)
xAx	A Port Bits
хВх	B Port Bits

# **FUNCTION TABLE (1)**

1 <mark>OE</mark>	2 <mark>0E</mark>	Description
Н	Н	Disconnect
L	Н	Connect 1A to 1B
Н	L	Connect 2A to 2B
L	L	Connect 1A to 1B and 2A to 2B

### NOTE:

1. H = HIGH L = LOW

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Operating Conditions:  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $VCC = 5.0V \pm 5\%$ 

Symbol	Parameter	Т	est Conditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
VIH	Control Input HIGH Voltage	Guaranteed Logic	HIGH Level	2	_	_	٧
VIL	Control Input LOW Voltage	Guaranteed Logic	Guaranteed Logic LOW Level		_	0.8	٧
Іін	Control Input HIGH Current	Vcc = Max.	VI = VCC	_	_	±1	μA
lıL	Control Input LOW Current		V <sub>I</sub> = GND	_	_	±1	]
lozн	Current during	Vcc = Max., Vo = 0	0 to 5V	_	_	±1	μA
lozL	Bus Switch DISCONNECT			_	_	±1	
Vık	Clamp Diode Voltage	Vcc = Min., I <sub>IN</sub> = -	-18mA	_	-0.7	-1.2	V
loff	Switch Power Off Leakage	Vcc = 0V, Vin or V	$VCC = 0V$ , $VIN \text{ or } VO \le 5.5V$		_	±1	μA
Icc	Quiescent Power Supply Current	Vcc = Max., Vin =	GND or Vcc	_	0.1	3	μA

# **BUS SWITCH IMPEDANCE OVER OPERATING RANGE**

Following Conditions Apply Unless Otherwise Specified: Operating Conditions:  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $VCC = 5.0V \pm 5\%$ 

Symbol	Parameter	Test Conditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Ron	Switch CONNECT Resistance, A to B(2)	Vcc = Min., VIN = 0V	-	5	7	Ω
		Ion = 30mA				
		Vcc = Min., VIN = 2.4V	_	10	15	
		ION = 15mA				
los	Short Circuit Current, A to B(3)	A(B) = 0V, B(A) = VCC	100	_	_	mA

### NOTES:

- 1. Typical values are at Vcc = 5.0V, +25°C ambient.
- 2. The voltage drop between the indicated ports divided by the current through the switch.
- 3. Not more than one output should be shorted at one time. Duration of the test should not esceed one second.

# **POWER SUPPLY CHARACTERISTICS**

Symbol	Parameter	Test C	onditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit
$\Delta$ lcc	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = Max.$ $V_{IN} = 3.4V^{(3)}$		_	0.5	1.5	mA
ICCD	Dynamic Power Supply Current <sup>(4)</sup>	Vcc = Max. Outputs Open 1 Enable Pin Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	120	160	μΑ/ MHz/ Enable
Ic	Total Power Supply Current <sup>(6)</sup>	Vcc = Max. Outputs Open 2 Enable Pins Toggling	VIN = VCC VIN = GND	_	2.4	3.2	mA
		fi = 10MHz 50% Duty Cycle	VIN = 3.4 VIN = GND	_	2.9	4.7	

#### NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. CPD = ICCD/VCC

CPD = Power Dissipation Capacitance

6. IC = IQUIESCENT + INPUTS + IDYNAMIC

 $IC = ICC + \Delta ICC DHNT + ICCD (fiN)$ 

Icc = Quiescent Current

 $\Delta$ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)

DH = Duty Cycle for TTL Inputs High

NT = Number of TTL Inputs at DH

ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

fi = Input Frequency

N = Number of Switches Toggling at fi

All currents are in milliamps and all frequencies are in megahertz.

## SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Conditions:  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $VCC = 5.0V \pm 5\%$ 

Description	Min. <sup>(2)</sup>	Тур.	Max.	Unit
Data Propagation Delay	_	_	0.25	ns
A to B, B to A <sup>(2)</sup>				
Switch CONNECT Delay	1.5	_	6.5	ns
x <del>OE</del> to A or B				
Switch DISCONNECT Delay	1.5	_	5.5	ns
x <del>OE</del> to A or B				
Charge Injection During Switch DISCONNECT,	_	1.5	_	pC
	Data Propagation Delay A to B, B to A <sup>(2)</sup> Switch CONNECT Delay xOE to A or B Switch DISCONNECT Delay xOE to A or B	Data Propagation Delay         —           A to B, B to A <sup>(2)</sup> Switch CONNECT Delay           Switch DISCONNECT Delay         1.5           Switch DISCONNECT Delay         1.5           xOE to A or B         Charge Injection During Switch DISCONNECT,         —	Data Propagation Delay         —         —           A to B, B to A <sup>(2)</sup> —         —           Switch CONNECT Delay         1.5         —           xOE to A or B         —         —           Switch DISCONNECT Delay         1.5         —           xOE to A or B         —         —           Charge Injection During Switch DISCONNECT,         —         1.5	Data Propagation Delay         —         —         0.25           A to B, B to A <sup>(2)</sup> Switch CONNECT Delay         1.5         —         6.5           x OE to A or B         1.5         —         5.5           Switch DISCONNECT Delay         1.5         —         5.5           x OE to A or B         —         1.5         —         5.5           Charge Injection During Switch DISCONNECT,         —         1.5         —

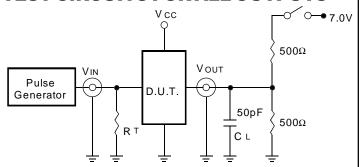
### NOTES:

- 1. See test circuit and waveforms.
- 2. The bus switch contributes no propagation delay other than the RC delay of the load interacting with the RC of the switch.
- 3. IQcII is the charge injection for a single switch DISCONNECT and applies to either single switches or multiplexers.

  IQDCII is the charge injection for a multiplexer as the multiplexed port switches from one path to another. Charge Injection is reduced becasue the injection from the DISCONNECT of the first path is compensated by the CONNECT of the second path.

# **TEST CIRCUITS AND WAVEFORMS**

# **TEST CIRCUITS FOR ALL OUTPUTS**



## **SWITCH POSITION**

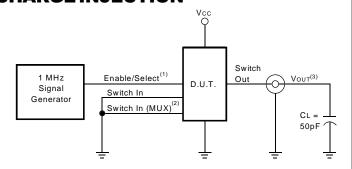
Test	Switch
Open Drain	
Disable Low	Closed
Enable Low	
All Other Tests	Open
	FCT LINK

### **DEFINITIONS:**

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

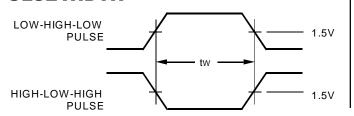
## **CHARGE INJECTION**



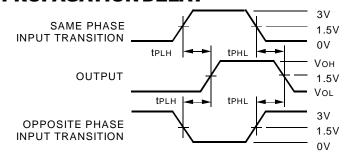
### NOTES:

- Select is used with multiplexers for measuring IQDCII during multiplexer select. During all other tests Enable is used.
- 2. Used with multiplexers to measure IQDCII only.
- 3. Charge Injection =  $\Delta$ VouT CL, with Enable toggling for IQclI or Select toggling for IQDCII.  $\Delta$ VouT is the change in VouT and is measured with a 10M $\Omega$  probe.

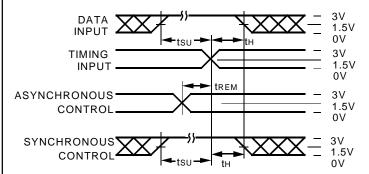
# **PULSE WIDTH**



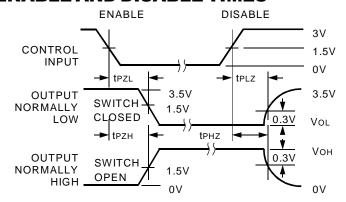
# PROPAGATION DELAY



# **SET-UP, HOLD, AND RELEASE TIMES**



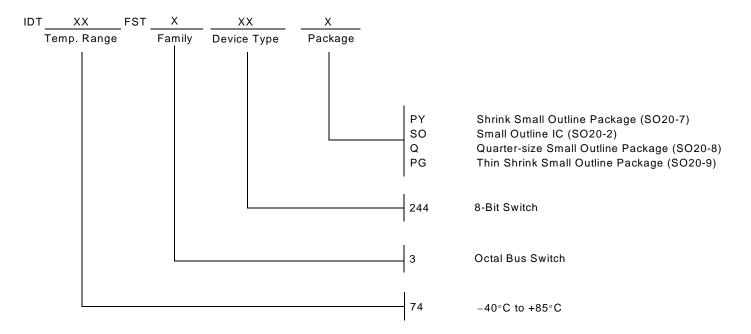
## **ENABLE AND DISABLE TIMES**



### NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- 2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz: tF ≤ 2.5ns: tR ≤ 2.5ns

# **ORDERING INFORMATION**





**CORPORATE HEADQUARTERS** 

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